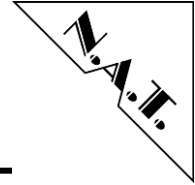


**NAMC-MPX
CPU AMC Module
Technical Reference Manual V1.2
HW Revision 1.2**

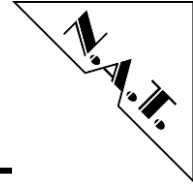


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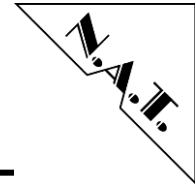
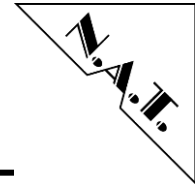
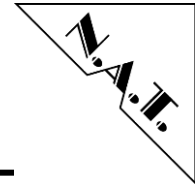


Table of Contents

DISCLAIMER	3
TABLE OF CONTENTS	4
LIST OF TABLES	6
LIST OF FIGURES	6
CONVENTIONS	7
1 INTRODUCTION	8
2 OVERVIEW	9
2.1 MAJOR FEATURES.....	9
2.2 BLOCK DIAGRAM	10
2.3 LOCATION DIAGRAM	11
3 BOARD FEATURES	12
3.1 CPU (MPX2020 EXTENSION BOARD)	12
3.2 MEMORY	12
3.2.1 <i>DDR2 SDRAM (MPX2020 Extension Board)</i>	12
3.2.2 <i>FLASH (MPX2020 Extension Board)</i>	12
3.2.3 <i>Micro SD-Card Slot (NAMC-MPX Base Board)</i>	12
3.3 FPGA	12
3.4 PCI EXPRESS AND SRIO INTERFACE	13
3.5 ETHERNET	13
3.5.1 <i>Front Panel Ethernet</i>	13
3.5.2 <i>Backplane Ethernet</i>	13
3.6 iTDM	13
3.7 BACKPLANE TDM.....	13
3.8 USB INTERFACE	14
3.9 RS232 INTERFACE.....	14
3.10 AMC CLOCK INTERFACE.....	14
3.11 I ² C-DEVICES AND IPMB	14
4 HARDWARE	15
4.1 AMC PORT DEFINITION	15
4.2 FRONT PANEL AND LED	16
4.3 CONNECTORS AND SWITCHES	17
4.3.1 <i>CON1: AMC Connector</i>	18
4.3.2 <i>J1: Micro SD Card Slot</i>	20
4.3.3 <i>J3: USB Connector</i>	20
4.3.4 <i>JP1: RS232 Connector</i>	20
4.3.5 <i>P1: MXP JTAG Connector</i>	20
4.3.6 <i>S1/S2: RJ45 Ethernet</i>	21
4.3.7 <i>S3: RS232 Front Panel Connector</i>	21
4.3.8 <i>ST1/ST2: Extension Module Connector</i>	21
4.3.9 <i>SW1: Hot Swap Switch</i>	21
4.3.10 <i>DIP SW2: Boot Mode Select / Reserved</i>	21



4.3.10.1	DIP SW2: Switch 1 – Boot Mode Select Switch	22
5	NAMC-MPX PROGRAMMING NOTES	23
5.1	FPGA MEMORY MAP	23
5.2	FPGA REGISTER DESCRIPTION GENERAL PURPOSE STATUS REGISTERS - 0x00..0x1FF	23
5.2.1.1	FPGA Register Description – PCB_VERS – 0x00	24
5.2.1.2	FPGA Register Description – DEV_VERS / FPGA_VERS – 0x02	24
5.2.1.3	FPGA Register Description – TEST_VAL_1 – 0x04	24
5.2.1.4	FPGA Register Description – TEST_VAL_2 – 0x06	24
5.2.1.5	FPGA Register Description – BOARD_ID – 0x08	24
5.2.1.6	FPGA Register Description – DIP_SW_ST / FPGA_PIN_ST – 0x0A	25
5.2.1.7	FPGA Register Description – CARRIER_ID / GEO_ADDRESS – 0x10	25
5.2.1.8	FPGA Register Description – FPGA_INF_1 / FPGA_INF_2 – 0x12	25
6	BOARD SPECIFICATION	26
7	INSTALLATION	27
7.1	SAFETY NOTE	27
7.2	INSTALLATION PREREQUISITES AND REQUIREMENTS	28
7.2.1	<i>Requirements</i>	28
7.2.2	<i>Power supply</i>	28
7.2.3	<i>Automatic Power Up</i>	28
7.3	STATEMENT ON ENVIRONMENTAL PROTECTION	29
7.3.1	<i>Compliance to RoHS Directive</i>	29
7.3.2	<i>Compliance to WEEE Directive</i>	29
7.3.3	<i>Compliance to CE Directive</i>	30
7.3.4	<i>Product Safety</i>	30
7.3.5	<i>Compliance to REACH</i>	30
8	KNOWN BUGS / RESTRICTIONS	31
	APPENDIX A: REFERENCE DOCUMENTATION	32
	APPENDIX B: DOCUMENT’S HISTORY	33

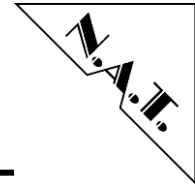


List of Tables

Table 1:	List of used abbreviations	7
Table 2:	AMC Port Definition	15
Table 3:	CON1: AMC Connector – Pin Assignment	18
Table 4:	J1: Micro SD-Card Slot – Pin Assignment	20
Table 5:	J3: USB Connector – Pin Assignment.....	20
Table 6:	JP1: RS232 Connector – Pin Assignment.....	20
Table 7:	P1: MPX JTAG Connector – Pin Assignment	20
Table 8:	S1/S2: RJ45 Connectors – Pin Assignment.....	21
Table 9:	S3: RS232 Front Panel Connector – Pin Assignment	21
Table 10:	DIP SW2: Pin-Assignment – Overview	21
Table 11:	DIP SW2: Switch 1 – Boot Mode Select – Pin-Assignment	22
Table 12:	FPGA Memory Map	23
Table 13:	NAMC-MPX with MPX2020 Specification – Overview.....	26

List of Figures

Figure 1:	NAMC-MPX – Block Diagram – Overview	10
Figure 2:	NAMC-MPX – Location Diagram Base Board – Overview	11
Figure 3:	NAMC-MPX – Front Panel	16
Figure 4:	NAMC-MPX – Connector and Switch Location – Overview	17



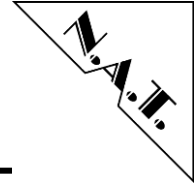
Conventions

If not otherwise specified, addresses and memory maps are written in hexadecimal notation, identified by *0x*.

The following table gives a list of the abbreviations used in this document.

Table 1: List of used abbreviations

Abbreviation	Description
AMC	Advanced Mezzanine Card
BDM	Background Debug Mode
CPU	Central Processing Unit
DDR SDRAM	Double Data Rate Synchronous Dynamic RAM
DIP SW	Dual In-Line Switch
DUART	Dual Universal Asynchronous Receiver/Transmitter
ECC	Error Correcting Code
EEPROM	Electrically Erasable PROM
FCLK	Fabric Clock
FPGA	Field Programmable Gate Array
GbE	Gigabit Ethernet
H.110	Timeslot Interchange Bus
I ² C	Inter-Integrated Circuit
IPMB	Intelligent Platform Management Bus
IPMI	Intelligent Platform Management Interface
iTDM	Internal TDM
JTAG	Joint Test Action Group
LED	Light Emitting Diode
MAC	Media Access Control
MCC	Memory Chip Controller
MPX	Microsys PPC Extendable Module
PCB	Printed Circuit Board
PCI(e)	Peripheral Component Interconnect (Express)
PLL	Phase Locked Loop
PHY	Physical Layer Device
(P)ROM	(Programmable) Read Only Memory
RAM	Random Access Memory
RGMII	Reduced Gigabit Media Independent Interface
SATA	Serial Advanced Technology Attachment
SD-Card	Secure Digital Memory Card
SDRAM	Synchronous Dynamic RAM
SerDes	Serializer/Deserializer
SRIO	Serial Rapid I/O
SPI FLASH	Serial Peripheral Interface FLASH
TCKL	Telecom Clock
TSI	Time Slot Interchanger
UART	Universal Asynchronous Receiver/Transmitter
USB	Universal Serial Bus
XAUI	10 GbE (via 4x 3.125 GB/s)



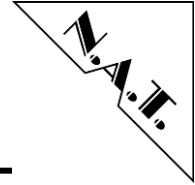
1 Introduction

The **NAMC-MPX** as modular platform element for MPX modules is dedicated to versatile embedded markets such as industrial controls, automation, (tele-)communication, defense&aerospace and medical area.

As carrier board based on AMC form factor, the **NAMC-MPX** provides a sophisticated infrastructure and offers two Ethernet, one USB, and one RS232 interface at the front panel. At the common options region of the AMC connector (port 0/1) are two GbE interfaces, two SATA (port 2 and port 3) as well as optional fat pipe interfaces as PCIe, SRIO, or XAUI at port 4-7.

The distinctive feature of the **NAMC-MPX** is the combination of N.A.T.'s basic AMC board with the powerful **MPX2020** module by MicroSys (**MicroSys PPC EXtendable Module**). This MPX module offers versatile I/O functionality as DUART, Ethernet, I²C and PCIe.

It will be possible to adopt other Microsys MPX extension boards to the **NAMC-MPX** carrier; what demands slight changes in design of the carrier board. For further information please contact N.A.T. Europe.



2 Overview

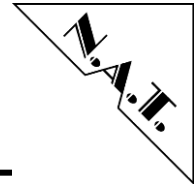
2.1 Major Features

Main features of the **NAMC-MPX** are determined by the extension board **MPX2020**:

- Freescale QorIQ P2020 with dual e500v2 Power Architecture @1.2 GHz
- Up to 2 GB DDR 2 SDRAM
- Up to 512 MB NAND-Flash

Features of the **NAMC-MPX** Base Board:

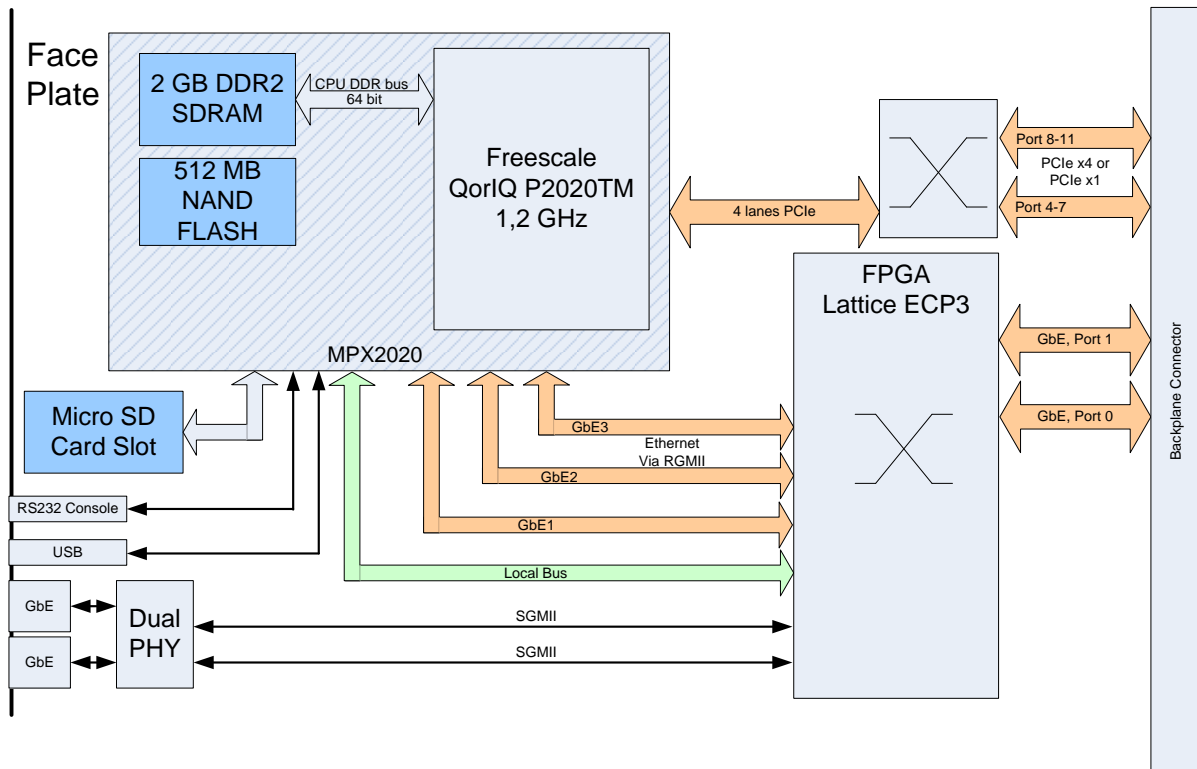
- Micro SD Card slot
- Lattice ECP3-FPGA
- PCIe Interface
- 2x 10/100/1000-BaseT Ethernet Front Panel Ethernet
- 2x Gigabit Ethernet at AMC Ports 0/1
- Optional: iTDM Interface
 - 1024 bidirectional 64kbit/s channels
 - 125 μ s-mode and 1ms-mode support (mixture possible)
- Optional: H.110 alike Backplane TSI bus
- USB Type A Jack on Front Panel
- RS232 Debug Connector on Front Panel (via Mini-USB Jacket)

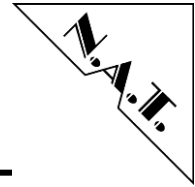


2.2 Block Diagram

The following figure shows a detailed block diagram of the **NAMC-MPX** base board with the **MPX2020** extension board attached.

Figure 1: NAMC-MPX – Block Diagram – Overview

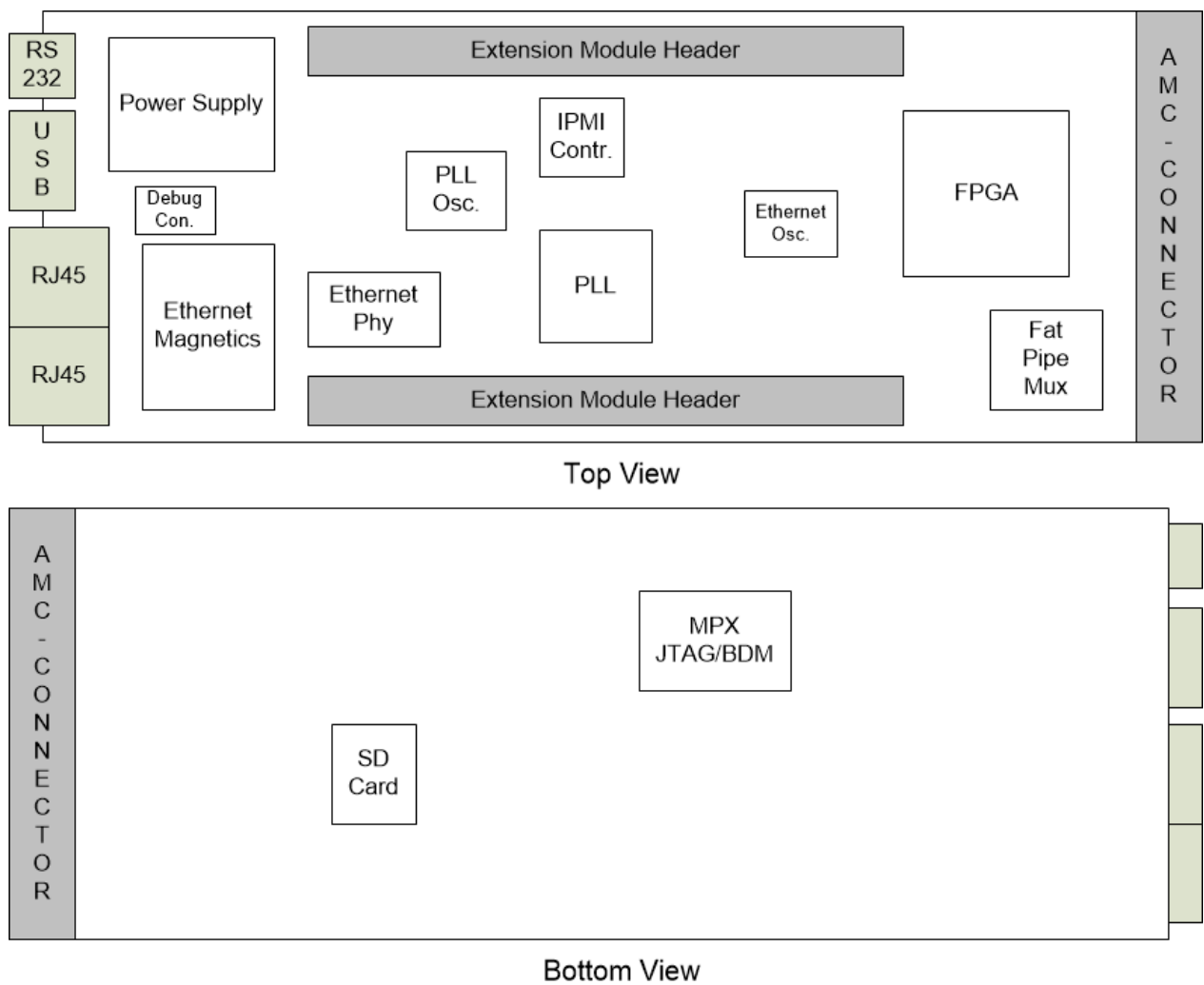




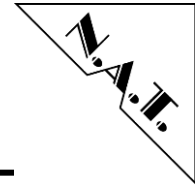
2.3 Location Diagram

The following figure shows the position of important components. Depending on the board type it might be that the board does not include all components named in the location diagram.

Figure 2: NAMC-MPX – Location Diagram Base Board – Overview



For further information regarding a location diagram of the **MPX2020** extension board please refer to the Microsys **MPX2020** specification.



3 Board Features

The **NAMC-MPX** can be divided into a number of functional blocks, which are described in the following paragraphs.

3.1 CPU (*MPX2020 Extension Board*)

The Freescale QorIQ P2020 is a versatile communications processor that integrates on one chip a high-performance microprocessor and many communications peripheral controllers that can be used in a variety of applications, particularly in communications and networking systems.

The core is a dual core e500v2 running at 1.2 GHz with 32 Kbytes of L1 cache and 512 Kbytes of Level 2 cache.

3.2 Memory

3.2.1 *DDR2 SDRAM (MPX2020 Extension Board)*

The DDR2 SDRAM memory with ECC support is 64 bit wide; up to 2 GB can be assembled. The interface is implemented in the QorIQ P2020. By programming several registers the RAM controller can be adapted to different RAM architectures.

3.2.2 *FLASH (MPX2020 Extension Board)*

FLASH memory is connected to the de-multiplexed upper 16 data bits D0 – 15 and to the latched address lines. De-multiplexing of the local address/data bus of the CPU, as well as address latching, is performed by an FPGA. It can be programmed by the CPU or through the BDM port.

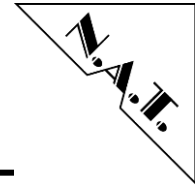
3.2.3 *Micro SD-Card Slot (NAMC-MPX Base Board)*

The **NAMC-MPX** is equipped with an SD-Card Slot that features up to 2 GB additional non-volatile memory.

3.3 FPGA

Beside some power/up reset logic the Lattice ECP3-FPGA is the Ethernet connection cross point on the **NAMC-MPX**. It establishes connectivity and performs the necessary conversion between:

- Front GbE 1
- Front GbE 2
- Backplane AMC Port 0 GbE
- Backplane AMC Port 1 GbE
- CPU RGMII interface 0
- CPU RGMII interface 1
- CPU RGMII interface 2



3.4 PCI Express and SRIO Interface

The P2020 CPU includes a 4-Lane SerDes unit, which is used to equip the **NAMC-MPX** with x4 PCIe by default. The configuration options include the following:

- PCIe x4 on Ports 4-7 or Ports 8-11
- PCIe x1 on Port 4 or Port 8

3.5 Ethernet

3.5.1 Front Panel Ethernet

On its face plate the **NAMC-MPX** is equipped with two RJ45 jacks, which offer a 10/100/1000-BaseT Ethernet interface each, handled by a Broadcom dual PHY device (BCM5482). The PHY's MAC side interfaces are then further connected to the FPGA. Within here it can be selected whether the CPU's two Ethernet controllers operate via the backplane Ethernet lines, via the front Ethernet ports or use a combination of both. Future FPGA versions could offer application specific switching functionality at this point.

3.5.2 Backplane Ethernet

The FPGA internal SerDes Ethernet is connected to the P2020's Ethernet MAC through RGMII interfaces, which are fed through the FPGA. It connects to the backplane Ethernet, the physical layer of which is 1000BaseX. Within FPGA logic the CPU Ethernet data is multiplexed with the iTDM data and transferred through the same physical port.

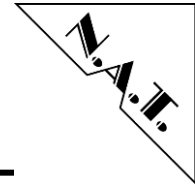
3.6 iTDM

The **NAMC-MPX** implements an optional serial iTDM backplane interface, the physical layer of which is 1000BaseX. The iTDM interface connects to Port 0/1 of the Common Options Region of the AMC backplane connector and shares the ports with the CPU Ethernet path.

One task of the FPGA residing on the **NAMC-MPX** is offering a powerful TDM to iTDM conversion engine to the board. This can be used for directly connecting channels from the line interface of other AMC boards to the **NAMC-MPX**.

3.7 Backplane TDM

The **NAMC-MPX** implements an 8 bit TDM interface, similar to H.110. The same throughput as with a complete H.110 bus is achieved by clocking the 8 backplane TDM lines with 32 MHz. Thus, every frame consists of 512 timeslots. The purpose of this TDM backplane bus is to establish 'private' TDM links to adjacent modules. The TDM interface is implemented in FPGA logic. It bridges to a module-internal TDM bus, which connects to the MCC ports of the P2020 QUICCEngine. The TDM interface connects to ports 12, 13 (data), and port 14 (Sync) of the Extended Options Region of the AMC connector.



3.8 USB Interface

The front panel connector J3 is a USB Type A jack that connects to the CPU internal USB controller. It can be used to implement various USB functionality covering both host or device behaviour.

3.9 RS232 Interface

The RS232 interface is physically presented in a Mini-USB Type B jacket. It is normally used for debugging purpose along with a standard terminal program (default baud rate: 19200).

3.10 AMC Clock Interface

The **NAMC-MPX** implements a very flexible clocking functionality concerning the AMC backplane clock ports TCLKA-D and FCLKA.

All TCLK ports are connected directly to the FPGA and can be used for reception of any clock or can be configured to drive a clock signal. This infrastructure can be used for distributing recovered reference clocks from the line interfaces or to synchronize the **NAMC-MPX** to an external clock.

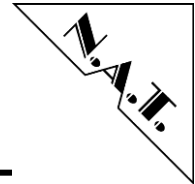
3.11 I²C-Devices and IPMB

The **NAMC-MPX** implements an IPMB interface consisting of an ATmega1284P IPMI-Microcontroller, a temperature sensor (LM95241 – I²C-Address: 0x56), and the Hot-Swap controller (LTC4215 – I²C-Address: 0x96).

Please note that the 7-bit I²C-Address is left aligned in the notation, meaning that in the most-right bit (LSB) the I²C R/W bit resides.

Additionally, the IPMB-Bus of the AMC connector is attached to the IPMI-Controller.

The IPMI-Controller manages also the geographical address as requested by the AMC specification.

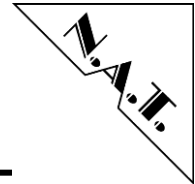


4 Hardware

4.1 AMC Port Definition

Table 2: AMC Port Definition

	Port #	AMC Port Mapping Strategy	Ports used as
Basic Connector	CLK1	Clocks	Reference Clock 1 / TCLKA
	CLK2		Reference Clock 2 / TCLKB
	CLK3		Reference Clock 3 / FCLKA
	0	Common Options Region	1000BaseX Ethernet Channel 1 (iTDM and CPU Ethernet), default
	1		1000BaseX Ethernet Channel 2 (iTDM and CPU Ethernet), redundant
	2		unassigned
	3		unassigned
	4	Fat Pipes	SerDes Lane 0
	5		SerDes Lane 1
	6		SerDes Lane 2
7	SerDes Lane 3		
Extended Connector	8	Region	SerDes Lane 0 Alternative
	9		SerDes Lane 1 Alternative
	10		SerDes Lane 2 Alternative
	11		SerDes Lane 3 Alternative
	12	Extended Options Region	TDM Bus D0-3 (H.110 extended)
	13		TDM Bus D4-7 (H.110 extended)
	14		optional clock lines (H.110 extended)/ unassigned
	15		Unassigned
	16		TCLKC / TCLKD
	17		Unassigned
	18		Unassigned
	19		Unassigned
	20		Unassigned



4.2 Front Panel and LED

The **NAMC-MPX** module is equipped with 4 bicolour LEDs integrated in the RJ45 interface jacks. They are driven by the Ethernet PHY and can be programmed to various link indication modes.

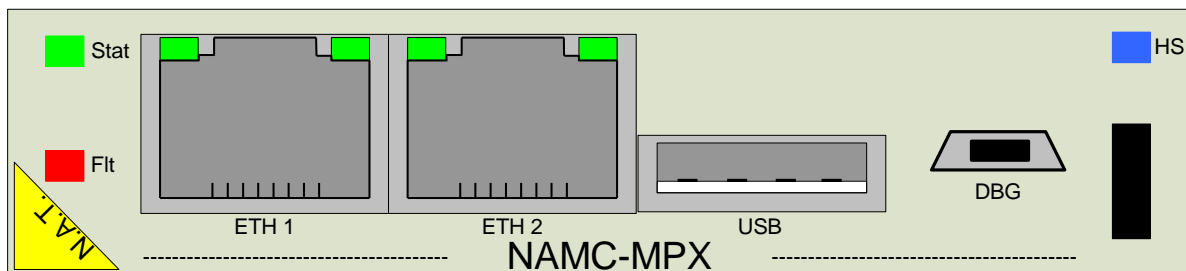
Additionally the module contains the standard AMC LEDs consisting of a fault indication LED controlled by the IPMI controller and a general purpose status LED controlled by the FPGA/CPU.

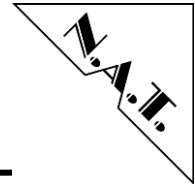
The Fault Indication LED turns to "On" if the temperature sensor registers a temperature value falling below or exceeding a threshold level. If the temperature returns to normal value, the LED is switched to "Off" again.

Standard behaviour of the status LED is as follows:

The LED is timely multiplexed to display the status of both backplane Ethernet links operating via AMC port 0/1 combined with the link status between the FPGA and the front Ethernet PHY device. A period of solid green indicates here a link on AMC port0, a period of fast green blinking indicates a link on AMC port 1 and a period of solid orange indicates a link between the front Ethernet PHY and the FPGA.

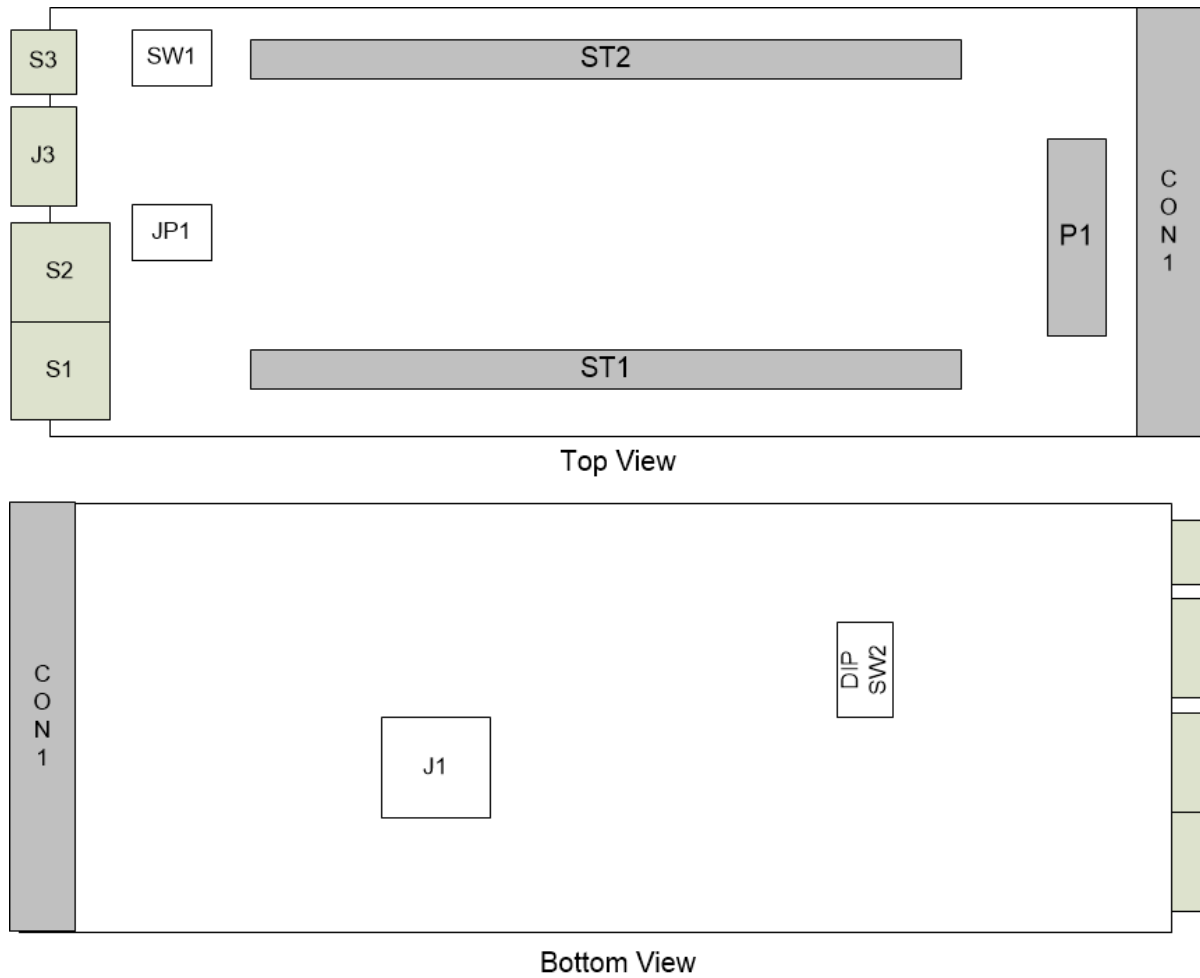
Figure 3: NAMC-MPX – Front Panel



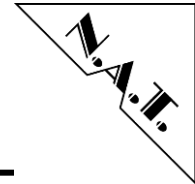


4.3 Connectors and Switches

Figure 4: NAMC-MPX – Connector and Switch Location – Overview



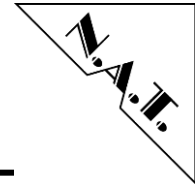
Please refer to the following tables to look up the connector pin assignment of the **NAMC-MPX**.



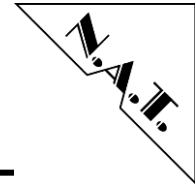
4.3.1 CON1: AMC Connector

Table 3: CON1: AMC Connector – Pin Assignment

Pin #	AMC-Signal	AMC-Signal	Pin #
1	GND	GND	170
2	PWR	TDI	169
3	/PS1	TDO	168
4	PWR_IPMB	/TRST	167
5	GA0	TMS	166
6	RESVD	TCK	165
7	GND	GND	164
8	RESVD	NC	163
9	PWR	NC	162
10	GND	GND	161
11	PORT0_TX_P	NC	160
12	PORT0_TX_N	NC	159
13	GND	GND	158
14	PORT0_RX_P	NC	157
15	PORT0_RX_N	NC	156
16	GND	GND	155
17	GA1	NC	154
18	PWR	NC	153
19	GND	GND	152
20	PORT1_TX_P	NC	151
21	PORT1_TX_N	NC	150
22	GND	GND	149
23	PORT1_RX_P	NC	148
24	PORT1_RX_N	NC	147
25	GND	GND	146
26	GA2	NC	145
27	PWR	NC	144
28	GND	GND	143
29	NC	NC	142
30	NC	NC	141
31	GND	GND	140
32	NC	TCLKD_P	139
33	NC	TCLKD_N	138
34	GND	GND	137
35	NC	TCLKC_P	136
36	NC	TCLKC_N	135
37	GND	GND	134
38	NC	NC	133
39	NC	NC	132
40	GND	GND	131
41	/ENABLE	NC	130
42	PWR	NC	129
43	GND	GND	128
44	PORT4_TX_P	RESVD	127



Pin #	AMC-Signal	AMC-Signal	Pin #
45	PORT4_TX_N	TDM_REF	126
46	GND	GND	125
47	PORT4_RX_P	TDM_FS	124
48	PORT4_RX_N	TDM_CLK	123
49	GND	GND	122
50	PORT5_TX_P	TDM7	121
51	PORT5_TX_N	TDM6	120
52	GND	GND	119
53	PORT5_RX_P	TDM5	118
54	PORT5_RX_N	TDM4	117
55	GND	GND	116
56	IPMB_SCL	TDM3	115
57	PWR	TDM2	114
58	GND	GND	113
59	PORT6_TX_P	TDM1	112
60	PORT6_TX_N	TDM0	111
61	GND	GND	110
62	PORT6_RX_P	PORT11_TX_P	109
63	PORT6_RX_N	PORT11_TX_N	108
64	GND	GND	107
65	PORT7_TX_P	PORT11_RX_P	106
66	PORT7_TX_N	PORT11_RX_N	105
67	GND	GND	104
68	PORT7_RX_P	PORT10_TX_P	103
69	PORT7_RX_N	PORT10_TX_N	102
70	GND	GND	101
71	IPMB_SDA	PORT10_RX_P	100
72	PWR	PORT10_RX_N	99
73	GND	GND	98
74	TCLKA_P	PORT9_TX_P	97
75	TCLKA_N	PORT9_TX_N	96
76	GND	GND	95
77	TCLKB_P	PORT9_RX_P	94
78	TCLKB_N	PORT9_RX_N	93
79	GND	GND	92
80	FCLKA_P	PORT8_TX_P	91
81	FCLKA_N	PORT8_TX_N	90
82	GND	GND	89
83	/PS0	PORT8_RX_P	88
84	PWR	PORT8_RX_N	87
85	GND	GND	86



4.3.2 J1: Micro SD Card Slot

J1 connects directly to the SD Card interface and offers the option to use Micro SD Cards as removable Flash Memory on the **NAMC-MPX** board.

Table 4: J1: Micro SD-Card Slot – Pin Assignment

Pin #	Signal	Signal	Pin #
1	SD_DAT2	SD_DAT3	2
3	SD_CMD	+3.3V	4
5	SD_CLK	GND	6
7	SD_DAT0	SD_DAT1	8

4.3.3 J3: USB Connector

Connector J3 offer access to the CPU’s USB interface.

Table 5: J3: USB Connector – Pin Assignment

Pin #	Signal	Signal	Pin #
1	VBUS	USB_D_N	2
3	USB_D_P	GND	4

4.3.4 JP1: RS232 Connector

The Debug Terminal Connector JP1 offers the option to connect to UART1 of the CPU to realize a serial terminal interface. This connector can be used as alternative to the front panel connector S3.

Table 6: JP1: RS232 Connector – Pin Assignment

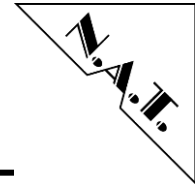
Pin #	Signal	Signal	Pin #
1	RxDA	GND	2
3	TxDA		

4.3.5 P1: MXP JTAG Connector

Connector P1 connects to the CPU’s JTAG Interface.

Table 7: P1: MPX JTAG Connector – Pin Assignment

Pin #	Signal	Signal	Pin #
1	MPX_TDO	GND	2
3	MPX_TDI	MPX_TRST	4
5	nc	+3.3V	6
7	MPX_TCK	MPX_CKSTI	8
9	MPX_TMS	nc	10
11	nSRST	GND	12
13	nHRST	nc	14
15	nMPX_CKSTO	GND	16



4.3.6 S1/S2: RJ45 Ethernet

Connectors S1 and S2 offer access to a 10/100/1000-BaseT Ethernet interface each.

Table 8: S1/S2: RJ45 Connectors – Pin Assignment

Pin #	Signal	Signal	Pin #
1	TRD0+	TRD0-	2
3	TRD1+	TRD2+	4
5	TRD2-	TRD1-	6
7	TRD3+	TRD3-	8

4.3.7 S3: RS232 Front Panel Connector

Connector S3 offers access to a RS232 interface connected to UART1 of the CPU.

Table 9: S3: RS232 Front Panel Connector – Pin Assignment

Pin #	Signal	Signal	Pin #
1	RTS_SCC1	RxD_SCC1	2
3	TxD_SCC1	CTS_SCC1	4
5	GND		

4.3.8 ST1/ST2: Extension Module Connector

Connectors ST1/ST2 connect to the extension module mounted on the **NAMC-MPX**. Please refer to the documentation of the respective MPX module for detailed information.

4.3.9 SW1: Hot Swap Switch

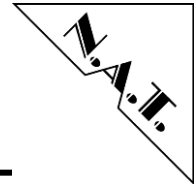
Switch SW1 is used to support Hot-Swapping of the module. It conforms to PICMG AMC.0.

4.3.10 DIP SW2: Boot Mode Select / Reserved

The table below gives an overview of the operating parameters configurable via DIP SW2. Details are given in the following subchapters.

Table 10: DIP SW2: Pin-Assignment – Overview

Switch #	Function
1	Boot Mode Select
2-8	Reserved



4.3.10.1 DIP SW2: Switch 1 – Boot Mode Select Switch

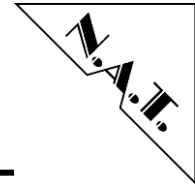
By operating switch 1 of DIP SW2 to ON, the SD-Card is selected as boot source. If switch 1 of DIP SW2 is turned to OFF, the FLASH memory is selected as boot source.

Table 11: DIP SW2: Switch 1 – Boot Mode Select – Pin-Assignment

DIP SW2 – Switch 1	Function
<p>ON</p> <p>1 2 3 4 5 6 7 8</p>	<p>Boot source: SD-Card</p>
<p>ON</p> <p>1 2 3 4 5 6 7 8</p>	<p>Boot source: FLASH</p>

Default:

Switch 1 of DIP SW2 is toggled to OFF; FLASH memory is selected for booting.



5 NAMC-MPX Programming Notes

5.1 FPGA Memory Map

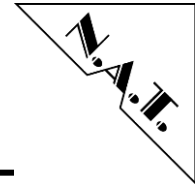
Table 12: FPGA Memory Map

	Logical Block	Description
0x00000..0x000ff	General Purpose Status	General Purpose Read-Only
0x00100..0x001ff	General Purpose Registers	General Purpose Read/Write
0x01000..0x01fff	FPGA SPI Flash Interface	
0x02000..0x02fff	Atmel SPI Interface	
0x10000..0x1ffff	GigabitEthernet Interface Block	
0x20000..0x2ffff	Local TDM Block	
0x80000..0xfffff	iTDM Block	

5.2 FPGA Register Description General Purpose Status

Registers - 0x00..0x1ff

	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
0x00	Reserved								PCB_VERS								
0x02	DEV_VERS								FPGA_VERS								
0x04	TEST_VAL_1																
0x06	TEST_VAL_2																
0x08	Board_ID																
0x0A	DIP_SW_ST								R.	FPGA_PIN_ST							
0x0C	Reserved																
0x0E	Reserved																
0x10	CARRIER_ID								GEO_ADDRESS								
0x12	FPGA_INF_1								FPGA_INF_2								



5.2.1.1 FPGA Register Description – PCB_VERS – 0x00

Bit	Name	Description	Default	Access
15..8		Reserved	0x00	Read Only
7..0	PCB_VERS	PCB version determined by level of unused pins hardcoded on PCB	HW init	Read Only

5.2.1.2 FPGA Register Description – DEV_VERS / FPGA_VERS – 0x02

Bit	Name	Description	Default	Access
15..8	DEV_VERS	Development version	na	Read Only
7..0	FPGA_VERS	FPGA version	na	Read Only

5.2.1.3 FPGA Register Description – TEST_VAL_1 – 0x04

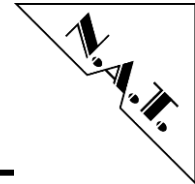
Bit	Name	Description	Default	Access
15..0	TEST_1	Random number for testing purposes	0xAA55	Read Only

5.2.1.4 FPGA Register Description – TEST_VAL_2 – 0x06

Bit	Name	Description	Default	Access
15..0	TEST_2	Random number for testing purposes	0xDEAD	Read Only

5.2.1.5 FPGA Register Description – BOARD_ID – 0x08

Bit	Name	Description	Default	Access
15..0	BOARD_ID	Holds the internal Board-ID	0x0b17	Read Only



5.2.1.6 FPGA Register Description – DIP_SW_ST / FPGA_PIN_ST – 0x0A

Bit	Name	Description	Default	Access
15..8	DIP_SW_ST	DIP Switch Status		Read Only
7		Reserved		Read Only
7..0	FPGA_PIN_ST	FPGA Pin Status – reflects assembly option		Read Only

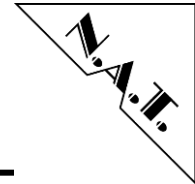
5.2.1.7 FPGA Register Description – CARRIER_ID / GEO_ADDRESS – 0x10

Bit	Name	Description	Default	Access
15..8	CARRIER_ID	Carrier Manager ID 0x80 + 2*Carrier Number	na	Read Only
7..0	GEO_ADDRESS	Geographical Address (Slot ID) 0x72: AMC1 0x74: AMC2 0x76: AMC3 0x78: AMC4 0x7A: AMC5 0x7C: AMC6 0x7E: AMC7 0x80: AMC8 0x82: AMC9 0x84: AMC10 0x86: AMC11 0x88: AMC12	na	Read Only

5.2.1.8 FPGA Register Description – FPGA_INF_1 / FPGA_INF_2 – 0x12

This register can be used to deliver further information from the Microcontroller to the FPGA; not used yet.

Bit	Name	Description	Default	Access
15..8	FPGA_INF_1	Tbd		Read Only
7..0	FPGA_INF_2	Tbd		Read Only

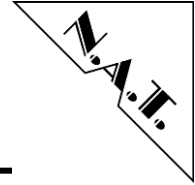


6 Board Specification

Table 13: NAMC-MPX with MPX2020 Specification – Overview

Processor*	Freescale QorIQ P2020 dual e500v2 Power Architecture 1.2 GHz
AMC-Module	Standard Advanced Mezzanine Card, single width
Front-I/O	2x RJ45 Ethernet, USB Type A, RS232 (Mini-USB)
Main Memory*	Up to 2 GB DDR2 SDRAM
FLASH PROM*	Up to 512 MB NAND-Flash
Removable FLASH	Micro-SD-Card slot
Firmware	OK1 and LINUX BSP
Power Consumption (NAMC-MPX with MPX2020 installed)	12V, 2.0A max.
Operating Temperature	0°C – +55°C with forced cooling
Storage Temperature	-40°C - +85°C
Humidity	10% – 90% rh non-condensing
Standards compliance	PICMG AMC.0 Rev. 2.0 PICMG AMC.1 Rev. 1.0 PICMG AMC.2 Rev. 1.0 (Type E2) PCI Express Base Specification Rev. 1.1 PICMG SFP.0 Rev. 1.0 (System Fabric Plane Format) PICMG SFP.1 Rev. 1.0 (Internal TDM) IPMI Specification v2.0 Rev. 1.0 PICMG µTCA.0 Rev. 1.0

* located on **MPX2020** extension board



7 Installation

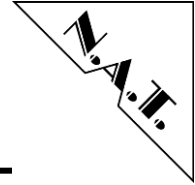
7.1 Safety Note

To ensure proper functioning of the **NAMC-MPX** during its usual lifetime take the following precautions before handling the board.

CAUTION

Electrostatic discharge and incorrect board installation and uninstallation can damage circuits or shorten their lifetime.

- Before installing or uninstalling the **NAMC-MPX** read this installation section
- Before installing or uninstalling the **NAMC-MPX**, read the Installation Guide and the User's Manual of the carrier board used, or of the uTCA system the board will be plugged into.
- Before installing or uninstalling the **NAMC-MPX** on a carrier board or both in a rack:
 - Check all installed boards and modules for steps that you have to take before turning on or off the power.
 - Take those steps.
 - Finally turn on or off the power if necessary.
 - Make sure the part to be installed / removed is hot swap capable, if you don't switch off the power.
- Before touching integrated circuits ensure to take all require precautions for handling electrostatic devices.
- Ensure that the **NAMC-MPX** is connected to the carrier board or to the uTCA backplane with the connector completely inserted.
- When operating the board in areas of strong electromagnetic radiation ensure that the module
 - is bolted the front panel or rack
 - and shielded by closed housing



7.2 Installation Prerequisites and Requirements

IMPORTANT

Before powering up check this section for installation prerequisites and requirements!

7.2.1 Requirements

The installation requires only:

- an ATCA carrier board, or a μ TCA backplane for connecting the **NAMC-MPX**
- power supply
- cooling devices

7.2.2 Power supply

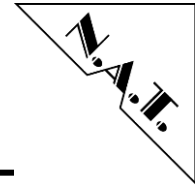
The power supply for the **NAMC-MPX** must meet the following specifications:

- required for the module: +12V / 2.0A max.

7.2.3 Automatic Power Up

In the following situations the **NAMC-MPX** will automatically be reset and proceed with a normal power up:

- The voltage sensor generates a reset
 - when +12V voltage level drops below 10V
 - when +3.3V voltage level drops below 3.08V
- when the carrier board / backplane signals a PCIe Reset.



7.3 Statement on Environmental Protection

7.3.1 Compliance to RoHS Directive

Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the "Restriction of the use of certain Hazardous Substances in Electrical and Electronic Equipment" (RoHS) predicts that all electrical and electronic equipment being put on the European market after June 30th, 2006 must contain lead, mercury, hexavalent chromium, polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDE) and cadmium in maximum concentration values of 0.1% respective 0.01% by weight in homogenous materials only.

As these hazardous substances are currently used with semiconductors, plastics (i.e. semiconductor packages, connectors) and soldering tin any hardware product is affected by the RoHS directive if it does not belong to one of the groups of products exempted from the RoHS directive.

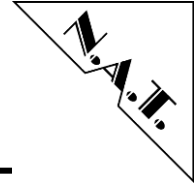
Although many of hardware products of N.A.T. are exempted from the RoHS directive it is a declared policy of N.A.T. to provide all products fully compliant to the RoHS directive as soon as possible. For this purpose since January 31st, 2005 N.A.T. is requesting RoHS compliant deliveries from its suppliers. Special attention and care has been paid to the production cycle, so that wherever and whenever possible RoHS components are used with N.A.T. hardware products already.

7.3.2 Compliance to WEEE Directive

Directive 2002/95/EC of the European Commission on "Waste Electrical and Electronic Equipment" (WEEE) predicts that every manufacturer of electrical and electronic equipment which is put on the European market has to contribute to the reuse, recycling and other forms of recovery of such waste so as to reduce disposal. Moreover this directive refers to the Directive 2002/95/EC of the European Commission on the "Restriction of the use of certain Hazardous Substances in Electrical and Electronic Equipment" (RoHS).

Having its main focus on private persons and households using such electrical and electronic equipment the directive also affects business-to-business relationships. The directive is quite restrictive on how such waste of private persons and households has to be handled by the supplier/manufacturer; however, it allows a greater flexibility in business-to-business relationships. This pays tribute to the fact with industrial use electrical and electronic products are commonly integrated into larger and more complex environments or systems that cannot easily be split up again when it comes to their disposal at the end of their life cycles.

As N.A.T. products are solely sold to industrial customers, by special arrangement at time of purchase the customer agreed to take the responsibility for a WEEE compliant disposal of the used N.A.T. product. Moreover, all N.A.T. products are marked according to the directive with a crossed out bin to indicate that these products within the European Community must not be disposed with regular waste.



If you have any questions on the policy of N.A.T. regarding the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the "Restriction of the use of certain Hazardous Substances in Electrical and Electronic Equipment" (RoHS) or the Directive 2002/95/EC of the European Commission on "Waste Electrical and Electronic Equipment" (WEEE) please contact N.A.T. by phone or e-mail.

7.3.3 Compliance to CE Directive

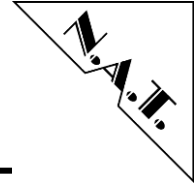
Compliance to the CE directive is declared. A 'CE' sign can be found on the PCB.

7.3.4 Product Safety

The board complies with EN60950 and UL1950.

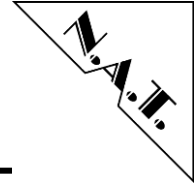
7.3.5 Compliance to REACH

The REACH EU regulation (Regulation (EC) No 1907/2006) is known to N.A.T. GmbH. N.A.T. did not receive information from their European suppliers of substances of very high concern of the ECHA candidate list. Article 7(2) of REACH is notable as no substances are intentionally being released by NAT products and as no hazardous substances are contained. Information remains in effect or will be otherwise stated immediately to our customers.



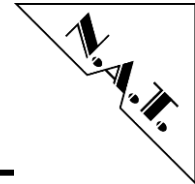
8 Known Bugs / Restrictions

none



Appendix A: Reference Documentation

- [1] Freescale, QorIQ P2020 Data Sheet, Rev.2, 8/7/2013
- [2] Lattice, ECP3 Handbook, Version 2.7EA, April 2014
- [3] Atmel, 8-bit Atmel Microcontroller Data Sheet, Rev. 8272E-AVR-04/2013



Appendix B: Document's History

Revision	Date	Description	Author
1.1	14.07.2011	initial revision	se/te
1.2	18.05.2013	Address, phone and fax updated, words updated / Telefon geändert, rote Wörter	fh
	15.10.2013	Adaption to HW Version 1.2 Added Connector Overview Adaption to new layout Typo correction, minor changes	se
	22.01.2014	Added FPGA Register Description	se
	13.08.2014	Added chapter 3.3 FPGA Update chapter 3.11 I ² C-Devices and IPMB Update chapter 4.2 Front Panel and LED Update chapter 7.3 RoHS-Directive / REACH Update Abbreviation List Minor changes	Se
	23.09.2014	Minor changes	se